

SCOPE OF ACCREDITATION

Electronics

Shenzhen Suntak Multilayer PCB CO.,Ltd.
Henggangxia Industry zone,xinyu road,Xinqiao Community,shajing street
Shenzhen, GUANGDONG 518132
China

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7119 Rev H - Nadcap Audit Criteria for Electronics Printed Boards (to be used on audits on/after 11 March 2018) (CANNOT BE COMBINED WITH AC7120 or AC7121)

- 03–Company Information (mandatory)
- 04–General Information (mandatory)
- 05–Process Control (mandatory)
- 06– Engineering Source File Processing (mandatory)
- 07.1– Material Control: General (mandatory)
- 07.2– Material Control: PrePreg
- 08.1– Imaging – Photoprocess (mandatory)
- 08.2.1– DES – Developing Photoimageable Resist (mandatory)
- 08.2.2– DES – Copper Etching of Inner Layers and Outer Layers (mandatory)
- 08.2.3– DES – Stripping of Resist Film and Etch–Resist Plating (mandatory)
- 08.2– Imaging – Develop–Etch–Strip (DES) and Strip–Etch–Strip (SES) (mandatory)
- 08.3– Etched Image Inspection (Manual or AOI) (mandatory)
- 09.1– Permanent Solder Mask: Solder Mask Application
- 09.2– Permanent Solder Mask: Solder Mask Exposing
- 09.3– Permanent Solder Mask: Solder Mask Develop and Cure
- 09– Permanent Solder Mask
- 10– Oxide Coating / Oxide Replacement Coating
- 11– Material Lay–Up and Lamination (mandatory)
- 12.1– Drilling: Mechanical Drilling
- 12.4– Drilling: Post–Drill Cleaning and Etchback
- 13.1– Epoxy Hole Fill and Planarization: Non–Conductive and/or Conductive Epoxy Hole Fill
- 13.2– Epoxy Hole Fill and Planarization: Planarization
- 14.1– Cooper Plating: Electroless Copper/Direct Metallization (mandatory)
- 14.2– Copper Plating: Electroplated Copper (mandatory)
- 14– Copper Plating: Electroplated Copper
- 15.3a– Final Finishes: Electroless (Chemical)/Immersion Plating Final Finish – ENIG

15.3– Final Finishes: Electroless (Chemical)/Immersion Plating Final Finish

15.4a– Electroplated Final Finish: Electroplated Nickel–Gold

16– Legend and Marking

17– Routing and Machining

18– Electrical Test – Functional (mandatory)

19– X–Ray Fluorescence (XRF)

20– Microsection Sample Selection, Preparation, and Inspection (mandatory)

21– Structural Integrity (mandatory)

22– Materials Lab (mandatory)

23– Chemistry Lab (mandatory)

24– Monthly Quality Conformance Testing

25– Final Validation (mandatory)

26– Packaging (mandatory)